

# MT18Ex

- MicroThin为附18  $\mu\text{m}$ 载体铜箔的超薄铜箔。  
MicroThin is ultra thin foil with 18  $\mu\text{m}$  carrier foil.
- 最适用于线宽/线距(L/S)=20/20~35/35之应用。  
Usable for fine pitch pattern L/S=20/20 - 35/35 formation.
- 与MT18SD-H相比较, 其更低的粗糙度更适用于极细线路之应用。  
Lower profile compare with MT18SD-H, more suitable for very fine pattern.

## 用途/Application

- IC封装基板  
/Semiconductor Package
- 高密度互连技术板  
/High Density Interconnect

## 构成/Composition



## 生产地点/Production Site

- 日本 / Japan
- 马来西亚/Malaysia

## 代表性特性数据/Representative data

	$\mu\text{m}$	Area weight (g/m <sup>2</sup> )	Laminate side Rz( $\mu\text{m}$ )	Tensile Strength (N/mm <sup>2</sup> )	Elongation (%)	Peel Strength (kg/cm) <sup>@FR-4</sup>
MT18Ex	1.5	20	2	-	-	1.2
	2	24	2	-	-	1.2
	3	33	2	-	-	1.2
	5	51	2	-	-	1.2

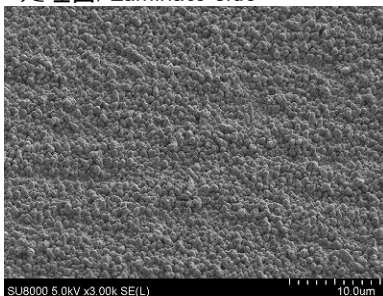
※上述表列为代表性数据非保证值

This is representative data, not guaranteed.

※Peel Strength为增镀到35  $\mu\text{m}$ 厚度之后的测试值

Evaluated after plated up to 35  $\mu\text{m}$ .

处理面/Laminate side



阻剂面/ resist side

